

Product Description

Panacol Structalit® adhesives are solvent free single or two-component adhesives. They are mostly based on epoxy resin and can be cured at room temperature or by exposure of heat. Structalit® products are designed for bonding, casting and protecting components in electronic and automotive industry.

Structalit® 5604 is a thermal curing, one component SMD adhesive, showing fast curing properties at low temperatures. The SMD adhesive shows a solid shock behavior. The material can be applied by using common industrial techniques: dispensers, screenprint, needle transfer. It is recommended to cure not more than 0,4g adhesive at once.

The product can be used as SMD adhesive for soldering temperatures in short processes (max. 5 minutes) at temperatures up to 270° C.

Curing Properties

The product is a one-component adhesive and can be cured with the addition of heat. Possible curing temperatures are listed in the table below.

Thermal curing	[min]
Time at 150°C	2
Time at 120°C	5
Time at 110°C	15
Time at 100°C	45

The curing times given are guidelines. The heating up of the joining members are not taken into account.

The final strength of the adhesive is reached at the earliest after 24 h.

Technical Data

Resin
Appearance

1K-epoxy
red

Uncured material

Viscosity [mPas] (Bohlin CVO, 25°C $\gamma=10s^{-1}$) <i>PE-Norm 029</i>	25 000 - 40 000
Density [g/cm ³] <i>PE-Norm 004</i>	1,1
Flash point [°C] <i>PE-Norm 050</i>	>100

Cured material

Hardness shore D <i>PE-Norm 006</i>	75 - 90
Temperature resistance [°C] <i>PE-Norm 065</i>	-40 - 180

Glass transition temperature DSC [°C] <i>PE-Norm 009</i>	115 - 135
Coefficient of linear expansion [ppm/K] below Tg <i>PE-Norm 017</i>	38,00
Coefficient of linear expansion [ppm/K] above Tg <i>PE-Norm 017</i>	212,00

Dielectric constant [10kHz]	3,30
Volume resistivity [Ohm*cm] <i>PE-Norm 040</i>	1E+12

Transport/Storage/Shelf Life

Trading unit	Transport	Storage	Shelf-life*
Cartridge	0°C - 10°C	0°C - 10°C	At delivery min. 4,5 months, max. 9 months
Other packages			

***Store in original, unopened containers!**

Instructions for Use

Surface preparation

The surfaces to be bonded should be free of dust, oil, grease or other dirt in order to obtain an optimal and reproducible bond.

For cleaning we recommend the cleaner IP® Panacol. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

Application

Our products are supplied ready to use. Depending on packaging they can be applied by hand directly from the container or semi or fully automatically. With automated application from the cartridge the adhesive is conveyed by a compressed air-operated displacement plunger via a valve in the needle. When metering low viscosity materials from bottles the adhesive is transported by a diaphragm valve. If help is required, please contact our application engineering department.

Adhesive and substrate may not be cold and must be warmed up to room temperature prior to processing.

For safety information refer to our safety data sheet.

Technical Datasheet

Structalit® 5604



Note

The product is free of heavy metals, PFOS and Phthalates and is conform to the EU-Directive 2011/65/EU "RoHS II" .

Our data sheets have been compiled to the best of our knowledge. The enclosed information describes characteristic properties, with no declaration of commitment. We recommend trials in order to confirm that our products satisfy the particular application requirements. For any additional technical support, please contact our application engineering department. For warranty claims, please refer to our standard terms and conditions.